

AMENDMENTS TO THE CLAIMS

1-17. (Canceled)

18. (Currently amended) An imaging device, comprising:

a die having a first surface containing an array of imaging elements; and

a transparent element adhesively attached to ~~said~~the die by an adhesive material and having a first surface facing the [[a]] first surface of ~~said~~the die, ~~said~~the first surface of ~~said~~the die having at least one adhesive flow restriction area for impeding flow of an adhesive across ~~said~~the first surface of ~~said~~the die, wherein ~~said~~the adhesive flow restriction area comprises at least one trench.

19. (Currently amended) The imaging device of claim 18, wherein ~~said~~the at least one trench has a curved shape.

20. (Currently amended) The imaging device of claim 18, wherein ~~said~~the at least one trench creates a perimeter around ~~said~~the array of imaging elements.

21. (Currently amended) The imaging device of claim 20, further comprising a second trench creating a perimeter around ~~said~~the at least one trench.

22. (Currently amended) The imaging device of claim 18, wherein ~~said~~the at least one trench extends from edge to edge of ~~said~~the die.

23-62. (Canceled)

63. (Currently amended) The imaging device of claim 18, wherein ~~said~~the transparent element is comprised of a material selected from the group consisting of glass, an optical thermoplastic material, a polyimide, a thermoset resin, a photosensitive gelatin, and a radiation curable resin.

64. (Currently amended) The imaging device of claim 18, wherein ~~said~~the adhesive material at an edge of ~~said~~the transparent element completely covers wire bonds electrically connecting ~~said~~the die to conductive lines.

65. (Currently amended) The imaging device of claim 18, wherein ~~said~~the die is associated with a substrate.

66. (Currently amended) The imaging device of claim 18, wherein ~~said~~the die is electrically connected to conductive tape by at least one conductive structure.

67. (Currently amended) The imaging device of claim 66, wherein ~~said~~the at least one conductive structure is a solder ball.

68. (Currently amended) The imaging device of claim 18, wherein ~~said~~the imaging element is comprised of an array of pixels, ~~said~~the pixels providing electrical signals corresponding to a response from light radiation.

69. (Currently amended) The imaging device of claim 18, wherein ~~said~~the imaging element is comprised of an array of pixels, ~~said~~the pixels capable of displaying an image corresponding to electrical signals.

70. (Currently amended) The imaging device of claim 18, wherein a vacant space between ~~said~~the transparent element and ~~said~~the array of imaging elements is hermetically sealed by ~~said~~the adhesive material.

71-78 (Cancelled).